

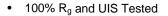
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## N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A)		
100	0.015 at V <sub>GS</sub> = 10 V	19		

#### **FEATURES**



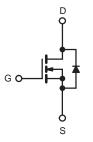




RoHS

#### **APPLICATIONS**

- Synchronus Rectification in DC/DC and AC/DC Converters
- Industrial and Motor Drive applications



N-Channel MOSFET

501-223
DOGG

COT 222

<b>ABSOLUTE MAXIMUM RATINGS</b> T <sub>A</sub> = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		$V_{DS}$	100	V	
Gate-Source Voltage		$V_{GS}$	± 20	V	
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C	I <sub>D</sub>	19		
Continuous Dialit Current (1) = 175 C)	T <sub>A</sub> = 70 °C	טי [	13	A	
Pulsed Drain Current		I <sub>DM</sub>	76		
Avalanche Current		I <sub>AS</sub>	7.8		
Single Pulse Avalanche Energy		E <sub>AS</sub>	55	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	P <sub>D</sub>	19.5	W	
Maximum Fower Dissipation	T <sub>A</sub> = 70 °C	. п	12.5		
Operating Junction and Storage Temperature Range		$T_J,T_stg$	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 10 s	R <sub>thJA</sub>	30	45		
Maximum Junction-to-Ambient	Steady State	- I`thJA	50	65	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	7.5	20		

#### Notes:

a. Surface Mounted on 1" x 1" FR4 board.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250		26		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	5.6				
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.5		3.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Oata Valta va Basis Oamast	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μA	
Zero Gate Voltage Drain Current		$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = - 10 V	19			Α	
	Б	V <sub>GS</sub> = 10 V, I <sub>D</sub> =7 A		0.015	0.020	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5 V, I <sub>D</sub> = 5 A		0.027	0.035		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 7 A		17		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			1013			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		212		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			85			
T. 10 ( 0)	0	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}$		19	19	1	
Total Gate Charge	Qg			11			
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 50 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		9		nC	
Gate-Drain Charge	$Q_{gd}$			15		1	
Gate Resistance	$R_g$	f = 1 MHz		1.6		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			7			
Rise Time	t <sub>r</sub>	$V_{DS} = 50 \text{ V}, R_{L} = 15 \Omega$		9			
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 7 \text{ A}, V_{GS} = 10 \text{ V}, R_g = 1 \Omega$		18			
Fall Time	t <sub>f</sub>			12			
Turn-On Delay Time	t <sub>d(on)</sub>			10		ns	
Rise Time	t <sub>r</sub>	$V_{DS} = 50 \text{ V}, R_L = 15 \Omega$		13		- - -	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 5$ A, $V_{GS} = 4.5$ V, $R_g = 1$ $\Omega$		21			
Fall Time	t <sub>f</sub>			16			
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			19		
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				76	Α	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 1 A		0.5	1.0	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			40		ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L = 7 A dl/dt = 100 A/va T = 25 °C		35		nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		12		1	
Reverse Recovery Rise Time	t <sub>b</sub>			10		ns	

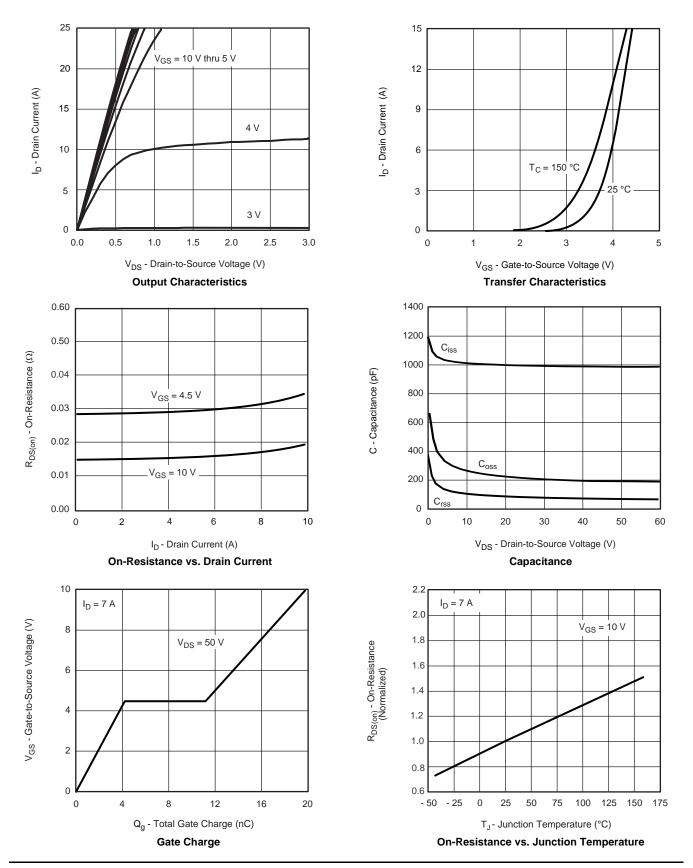
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$  b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



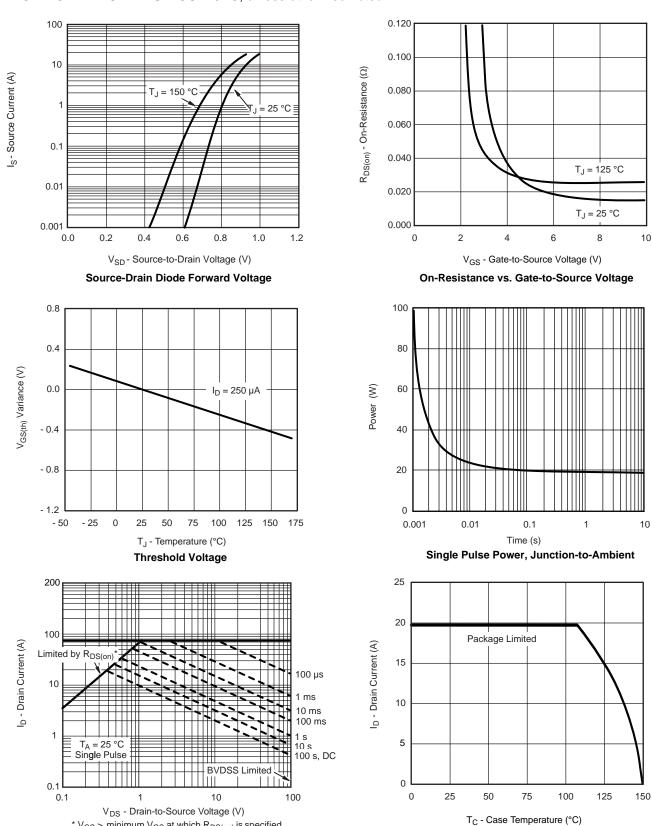




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\*  $V_{GS} > \mbox{minimum } V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area, Junction-to-Ambient

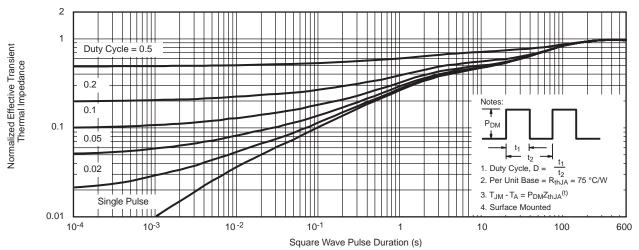


**Current Derating\*** 



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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



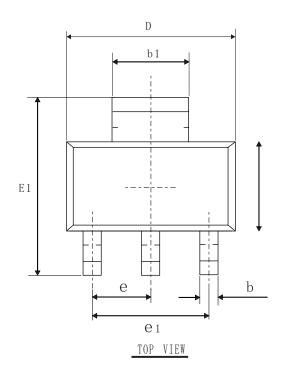
Normalized Thermal Transient Impedance, Junction-to-Ambient

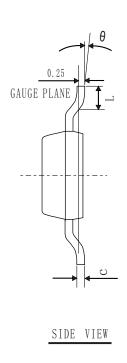
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

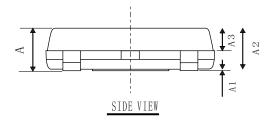




### SOT-223-3L PACKAGE OUTLINE







# COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX	
Α	-	-	1.95	
A1	0.00	0.05	0.16	
A2	1.35	1.60	1.85	
A3	0.65	0.90	1.15	
b	0.55	0.70	0.90	
b1	2.75	3.00	3.30	
С	0.18	0.30	0.42	
D	6.00	6.50	7.00	
Е	3.10	3.50	3.90	
E1	6.50	7.00	7.50	
e1	4.20	4.60	5.00	
L	0.78	-	1.28	
θ	0°	5°	10°	
е	2.3BSC			





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